Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

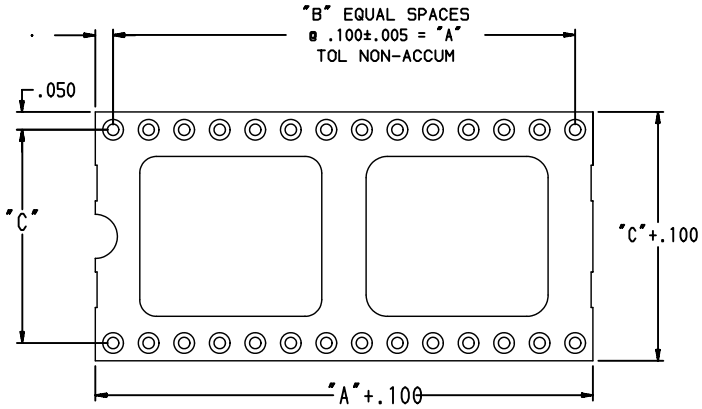
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

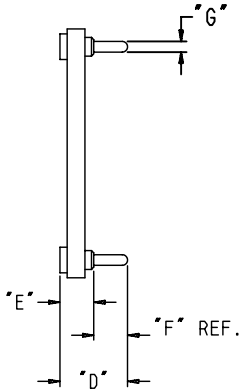
TABLE 2: LEAD FREE VERSION

TABLE 2 CONTACTS				DIMENSION			
[XXX]BLF	CLIP PLATING	SHELL PLATING	PCB HOLE	D	E	F	G
157BLF	100u" TIN OVER 50u" NICKEL	200u" TIN OVER 100u" NICKEL	ø.036±.003	.190	.095	.095	ø.030
160BLF	30u" GOLD OVER 50u" NICKEL	200u" TIN OVER 100u" NICKEL	ø.036±.003	.190	.095	.095	ø.030
208BLF	30u" GOLD OVER 50u" NICKEL	200u" TIN OVER 100u" NICKEL	ø.027±.003	.257	.132	.125	ø.020

TABLE 1

DISCONTINUANCE	PART NUMBER					DIMENSION		
OBSOLETE	DIP050-[1]-[XXX]B(LF)					"A"	"B"	"C"
OBSOLETE			306			DISCONTINUED		
OBSOLETE			308			DISCONTINUED		
OBSOLETE			314			DISCONTINUED		
OBSOLETE			316			DISCONTINUED		
OBSOLETE			318			DISCONTINUED		
OBSOLETE			320			DISCONTINUED		
OBSOLETE			322			DISCONTINUED		
OBSOLETE			324			DISCONTINUED		
			328			DISCONTINUED		
OBSOLETE			624			DISCONTINUED		
OBSOLETE			628			1.300	13	.600
OBSOLETE			632			DISCONTINUED		
OBSOLETE			640			DISCONTINUED		
OBSOLETE			648			DISCONTINUED		

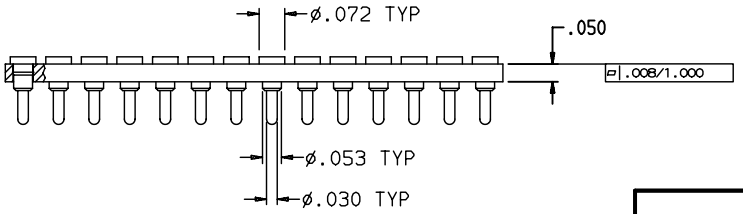




LEAD FREE PART NUMBER (SEE TABLE)
DIP050-[1]-[XXX]BLF

NOTES:

1. PRODUCT NUMBERING CODE:
   DIP050-NNN[XXX]B
   - TOTAL NO. OF POSITIONS.
   - ROW TO ROW SPACING.
2. INSULATOR MATERIAL:
   GLASS FILLED POLYESTER (PCT).
   RATED UL 94V-0, COLOR BLACK.
3. CONTACT MATERIAL:
   OUTER SHELL: BRASS ALLOY 360, 1/2 HARD PER QQ-B-626.
   INNEER CONTACT: BERYLLIUM COPPER, ALLOY 172 PER QQ-C-533.
4. CONTACT PLATING:
   GOLD PER MIL-G-45204, TYPE 1
   GRADE C, NICKEL PER QQ-N-290.
   TIN/LEAD OR LEAD-FREE PER MIL-P-81728, TYPE 1



(DIP050-628-[XXX]B SHOWN)

NOTE RoHS INFORMATION
-The "LF" products meet european union Directives and other country regulations as described in GS-22-008.
-The housing will whistand exposure to 260°C peak temperature for 20 seconds in a wave solder application with a 1.6mm minimum thick circuit board. See application notes/procedures if they are available.
-Packaging spec: see GS-14-920.

rev	ecn no	dr	date
A	V00857	DLW	5/04/00
B	V12187	DRW	12/09/01
C	V21006	RPM	6/06/02
D	V03-0323	HTB	18/03/03
E	LS06-0004	LGO	17/01/06
F	LS07-0141	HLE	2007/05/21
G	LS07-0271	HLE	2007/10/29

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Dr	D. WOLFORD	4/05/00
Eng	A.VASBINDER	4/05/00
Chr	A.VASBINDER	4/05/00
Appr	A.VASBINDER	4/05/00

surface ISO 1302 | tolerance std ISO 406 ISO 1101
TOLERANCES UNLESS OTHERWISE SPECIFIED

ANGULAR	LINEAR		
		0.X	±0.1
		0.XX	±0.1
0.XX° ±2°		0.XXX	±0.1

Product family PGA

projection | inch

size A3 | Scale 1:1

ECN LS07-0271

Spec ref -

title: DIP SOCKETS, 100 C/L (LOW PROFILE)

dwg no 58709 | Rev. G

catalog no -

CUSTOMER | sheet 1 of 1

REV F - 2006-04-17

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